

04-05-1999

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1 Name of conveying party(ies):
LING-CHEN KUNG AND TSUNG-YAO CHU2 Name and address of receiving party(ies):
INDUSTRIAL TECHNOLOGY RESEARCH INSTITUTE
195 Sec. 4 Chung Hsing Road
Chutung, Hsinchu, Taiwan 10
R.O.C.

Execution Date: January 20, 1999

Additional name(s) & address(es) attached ☐ Yes ☒ No

4 Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: 01-20-99

A. Patent Application No(s).

B. Patent No(s)

Additional numbers attached? ☐ Yes ☒ No

09. 274611

5 Name and address of party to whom correspondence
concerning document should be mailed:RANDY W. TUNG
Tung & Associates
838 W. Long Lake Road
Suite 120
Bloomfield Hills, Michigan 48302

6 Total number of applications and patents involved:

1

7 Total fee (37 CFR 3.41)

\$40.00

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*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*Randy W. Tung
Name of Person Signing
Registration No. 31,311

Signature

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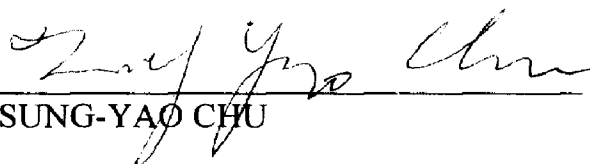
WHEREAS, we, LING-CHEN KUNG AND TSUNG-YAO CHU, have invented certain improvements in WAFER LEVEL PACKAGING METHOD AND DEVICES FORMED for which we are about to make application for Letters Patent of the United States; and

WHEREAS, INDUSTRIAL TECHNOLOGY RESEARCH INSTITUTE of 195 Sec. 4, Chung Hsing Road, Chutung, Hsinchu, Taiwan 310, R.O.C, is desirous of acquiring the entire right, title and interest in and to said invention;

NOW, THEREFORE, in consideration of One Dollar (\$1.00) and other good and valuable consideration, the receipt of which is hereby acknowledged, we, LING-CHEN KUNG AND TSUNG-YAO CHU, by these presents, do hereby sell, assign and transfer unto the said corporation and its assigns, for the territory of the United States of America and all foreign countries, the entire right, title and interest, including all priority rights under the International Convention associated with each country of the Union, in and to said invention as described in the patent application executed by us on the 20th day of January, 1999, preparatory to obtaining Letters Patent of the United States thereon, and in and to said application and any Letters Patent that may be granted in pursuance of said application and any divisional, continuation or continuation-in-part application thereof, and in and to any reissue of any such patent, and in and to any patent applications which may be filed on said invention in countries foreign to the United States and any Letters Patent granted thereon.

We further authorize said corporation to apply for foreign patents on said invention in its own name or through its designees, including subsidiaries, related companies or assignees, under the International Convention or otherwise, and we further agree to execute all papers, including those required for the United States and foreign applications, and to perform such other proper acts as said corporation or its designees the rights herein assigned.


LING-CHEN KUNG


TSUNG-YAO CHU

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